

## Si4286DY-T1-GE3-VB Datasheet

## Dual N-Channel 60 V (D-S) 175 °C MOSFET

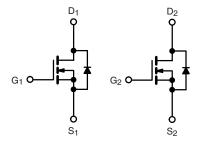
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.028			
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS}$ = 4.5 V	0.030			
I <sub>D</sub> (A) per leg	7			
Configuration	Dual			

### **SO-8 Dual** D<sub>2</sub> D<sub>1</sub> 6 D<sub>1</sub> 7 4 2 S<sub>2</sub> 1 G<sub>1</sub> S<sub>1</sub> Top View

#### FEATURES

- TrenchFET<sup>®</sup> power MOSFET
- 100 %  $\rm R_g$  and UIS tested





N-Channel MOSFET N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25 \degree C$ , unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V <sub>DS</sub>	60	V		
Gate-Source Voltage		V <sub>GS</sub>	± 20	V		
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	7			
	T <sub>C</sub> = 125 °C		4			
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	3.6	А		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	28			
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	18			
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	16.2	mJ		
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	Р	4	W		
	T <sub>C</sub> = 125 °C	P <sub>D</sub>	1.3	vv		
Operating Junction and Storage Temperature	Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	110	°C/W		
Junction-to-Foot (Drain)		R <sub>thJF</sub>	34	0/10		

#### Notes

a. Package limited.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. When mounted on 1" square PCB (FR4 material).

SPECIFICATIONS ( $T_C = 25 \ ^{\circ}C$ ,	unless otherv	vise noted)					
PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \ \mu A$		60	-	-	v
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		2.0	2.5	
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V	-	-	1	μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	20	-	-	A
		$V_{GS} = 10 V$	I <sub>D</sub> = 4.5 A-		0.028	-	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 125 °C	-	0.066	-	Ω
	20(0.1)	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 175 °C	-	0.081	-	
		$V_{GS} = 4.5 V$	I <sub>D</sub> = 4 A-	_	0.030	-	
Forward Transconductance f	9fs	V <sub>DS</sub>	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 4.5 \text{ A}$		15	-	S
Dynamic <sup>b</sup>	I	1	I	1	-		
Input Capacitance	C <sub>iss</sub>		= 0 V V <sub>DS</sub> = 25 V, f = 1 MHz	-	600	750	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	110	140	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	50	62	
Total Gate Charge <sup>c</sup>	Qg			-	11.7	18	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{GS} = 10 V$	$V_{DS} = 30 \text{ V}, I_D = 5.3 \text{ A}$	-	1.8	2.7	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	2.8	4.2	
Gate Resistance	Rg		f = 1 MHz		-	6	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>				7	11	
Rise Time <sup>c</sup>	t <sub>r</sub>	$\label{eq:VDD} \begin{array}{l} V_{\text{DD}}=30 \text{ V}, \ R_{\text{L}}=6.8 \ \Omega \\ I_{\text{D}}\cong 4.4 \ \text{A}, \ V_{\text{GEN}}=10 \ \text{V}, \ R_{g}=1 \ \Omega \end{array}$		-	3.3	5	- ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	22.4	33.5	
Fall Time <sup>c</sup>	tf			-	2.1	3.2	
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>	•					
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	28	А
Forward Voltage	V <sub>SD</sub>	IF :	= 2 A, V <sub>GS</sub> = 0 V	-	0.75	1.1	V

Notes

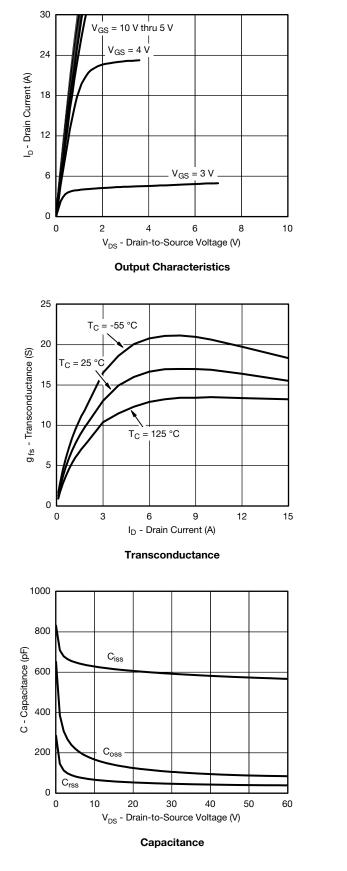
a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

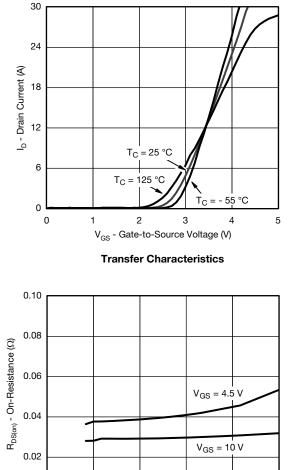
c. Independent of operating temperature.

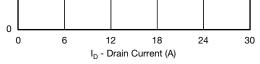
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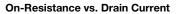


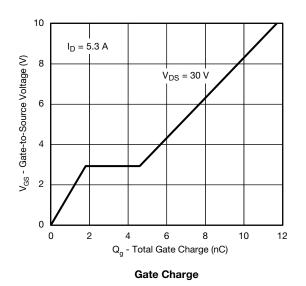
#### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)





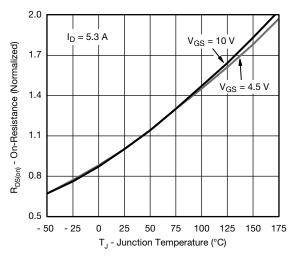




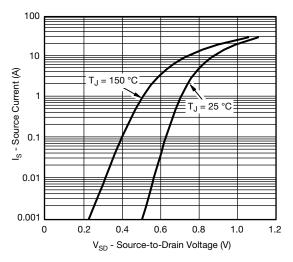




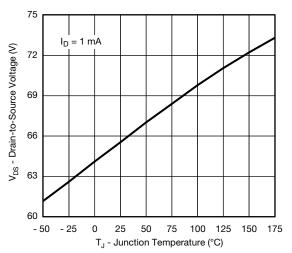
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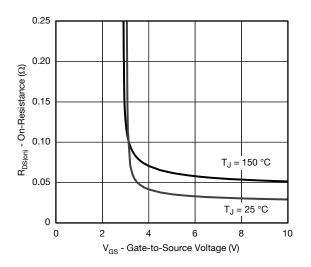
**On-Resistance vs. Junction Temperature** 



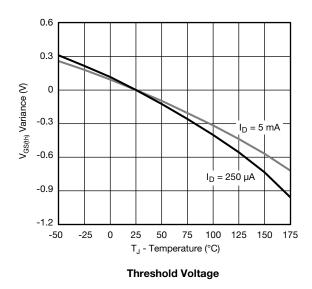
Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature

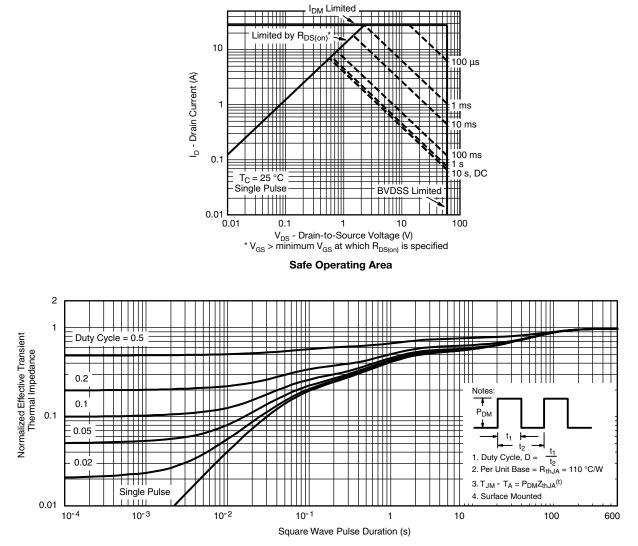


On-Resistance vs. Gate-to-Source Voltage





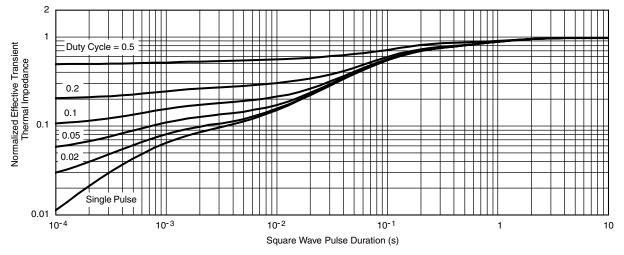
#### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



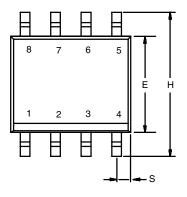
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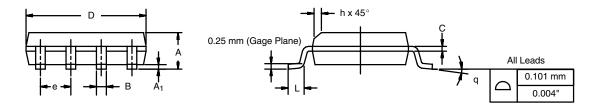


Normalized Thermal Transient Impedance, Junction-to-Foot



# SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012



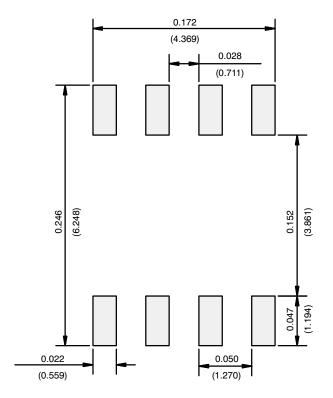


	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					

## Si4286DY-T1-GE3



**RECOMMENDED MINIMUM PADS FOR SO-8** 



Recommended Minimum Pads Dimensions in Inches/(mm)



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